

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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APPLICANT : TANAKA KIKINZOKU KOGYO KK;

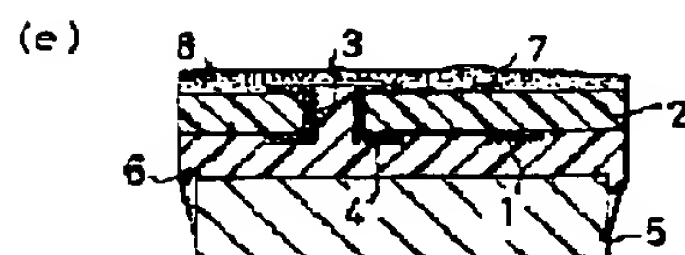
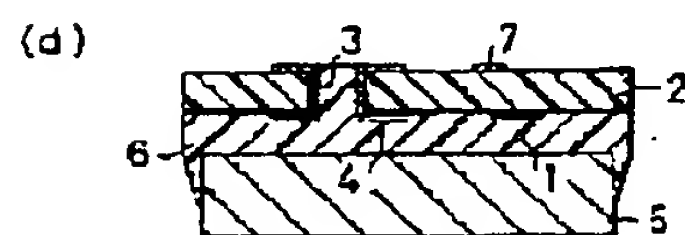
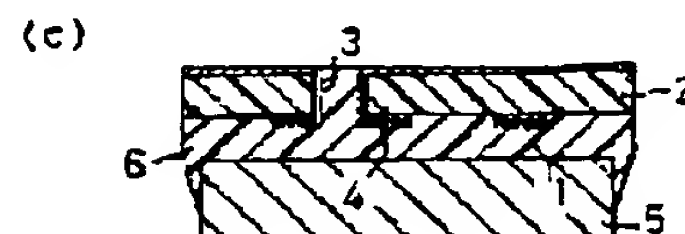
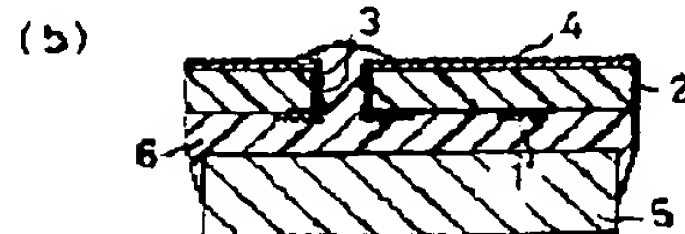
INVENTOR : ONODERA TAMOTSU;

INT.CL. : H05K 3/44 H05K 1/02

TITLE : MANUFACTURE OF METALLIC BASE  
SUBSTRATE

AF

Docket # 4231  
Inv: H. Hemz et al.  
USSN: 09/914,932  
Conf. # 5970



ABSTRACT : PURPOSE: To prevent a black treated surface and void from remaining and a circuit from bending.

CONSTITUTION: When a double-sided printed wiring board with a through-hole for improving heat dissipation property, etc., is manufactured by using a metallic plate 5, black treatment is performed after pattern formation on one side of a double-sided copper clad board. After a metallic plate is laminated and formed in the one surface wherein pattern formation is performed with a bonding layer 6 between, the other side of the double-sided copper clad board is mechanically polished and solder resist 8 is applied to the other side after performing pattern formation for it. Thereby, firm polishing is possible during mechanical polishing and mechanical strength of the other side is improved during lamination formation.

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